Board Characteristics - 8 LAYER BOARD

1. All dimensions are given in inches unless specified otherwise.
2. Material FR4, Tg 173°C.
3. General trace width/clearance on all layers is 5 mils. Special trace width/clearance of 2.5/2.5 mils in 4 small areas on top layer only. These 4 small areas are 0.055 x 0.055 inches each.
4. 1/2 oz copper for all layers.
5. Immersion Gold over copper, with min. Ni: 2.5-5 um; Au: 0.05-0.2 um
6. Apply Solder Mask over bare copper.
7. Silk screen on Component and Solder Sides.
8. FR4 tolerances: +/- 0.003 inches unless specified otherwise.
9. Interlayer spacing as specified.
10. Impedance control: 55 ohm +/- 10% on all 5 high traces, inner and outer layers.